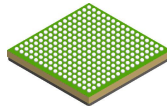


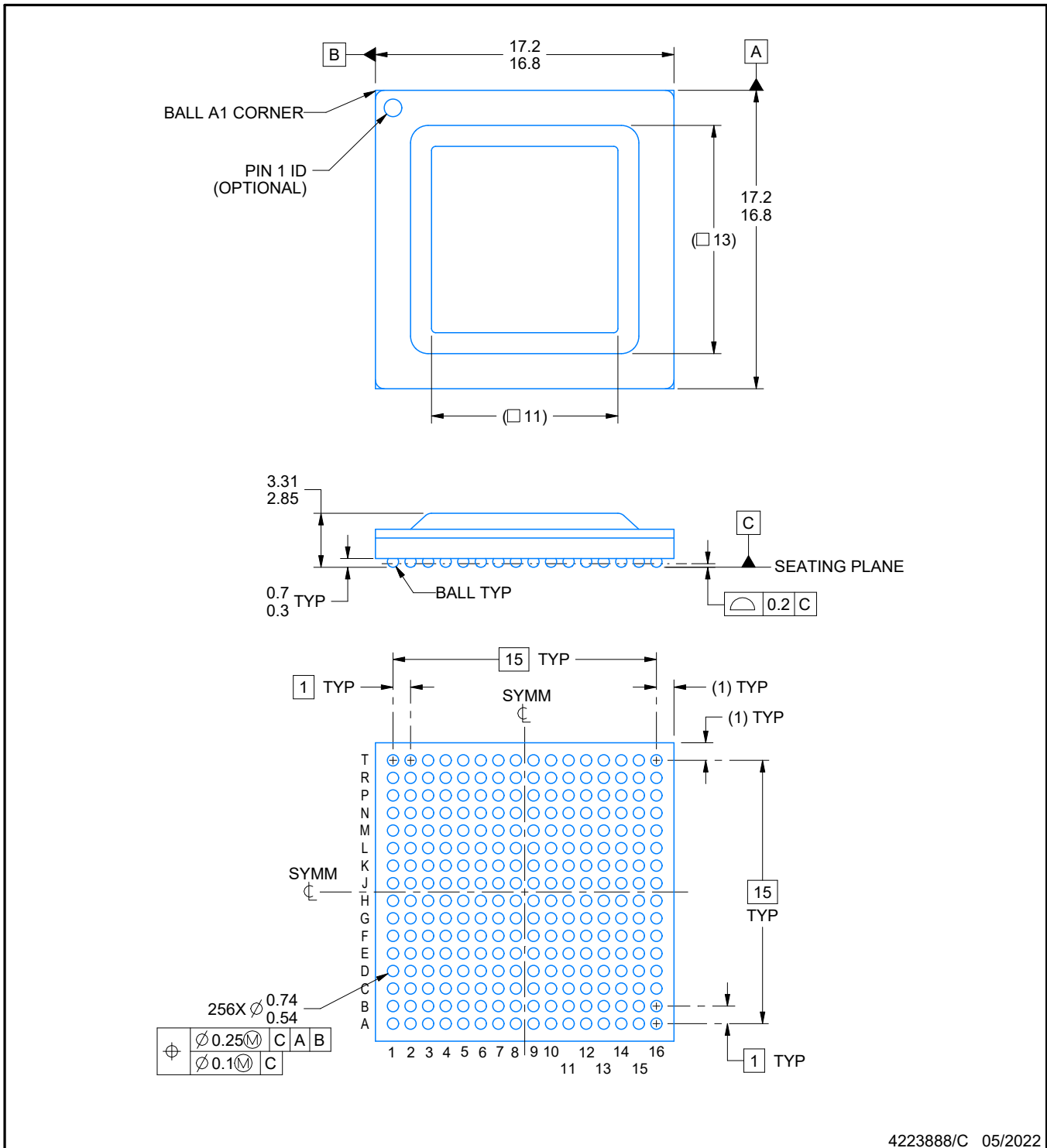
ACF0256A



PACKAGE OUTLINE

FCBGA - 3.31 mm max height

BALL GRID ARRAY



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NOTES:

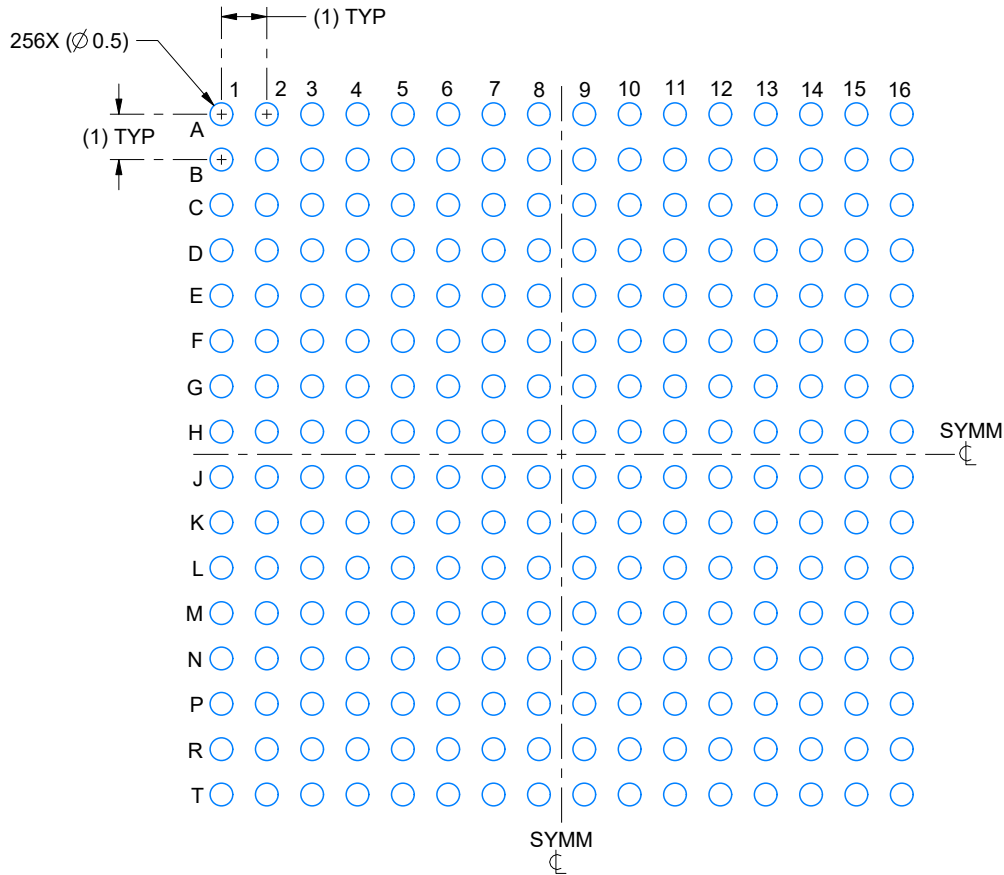
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Pb-Free die bump and solder ball.

EXAMPLE BOARD LAYOUT

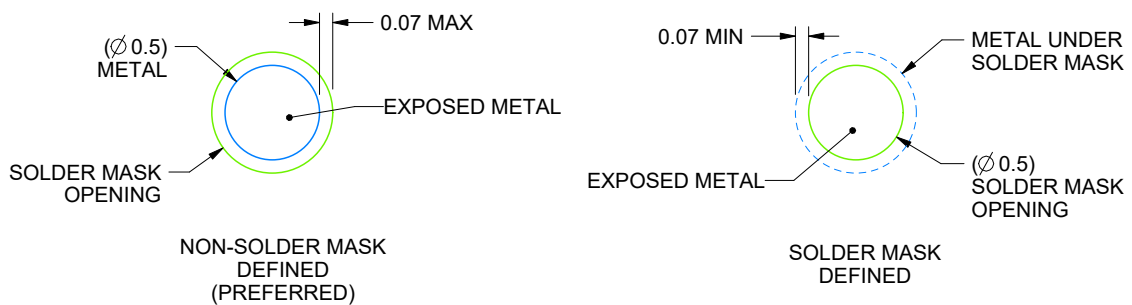
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FCBGA - 3.31 mm max height

BALL GRID ARRAY



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:6X



SOLDER MASK DETAILS
NOT TO SCALE

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NOTES: (continued)

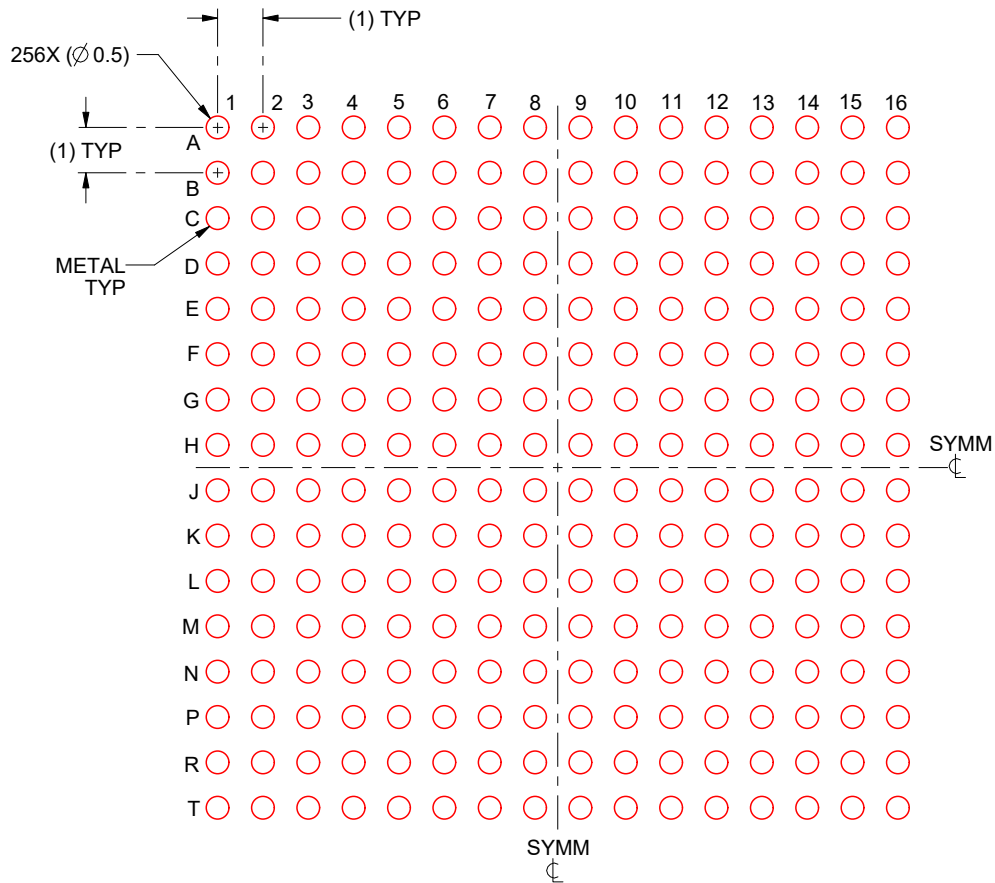
- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For more information, see Texas Instruments literature number SPRU811 (www.ti.com/lit/spru811).

EXAMPLE STENCIL DESIGN

ACF0256A

FCBGA - 3.31 mm max height

BALL GRID ARRAY



SOLDER PASTE EXAMPLE
BASED ON 0.15 mm THICK STENCIL
SCALE: 6X

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NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

REVISIONS

REV	DESCRIPTION	ECR	DATE	ENGINEER / DRAFTER
A	RELEASE NEW DRAWING	2167967	09/15/2017	K. LEWIS / K. SINCERBOX
B	256X (∅ 0.5) WAS 256X (∅ 0.55); 256X (∅ 0.5) WAS 256X ∅ 0.45;	2183797	10/23/2019	D. CHIN / K. SINCERBOX
C	3.31/2.85 WAS 3.31 MAX;	2199991	05/26/2022	S. O'CONNOR / K. SINCERBOX